**Product End-of-Life Disassembly Instructions**

**Product Category:** Notebooks and Tablet PCs

**Marketing Name / Model**
[List multiple models if applicable.]

HP ProBook x360 11 G3 Education Edition

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HPI products to remove components and materials requiring selective treatment, as defined by EU directive 2012/19/EC, Waste Electrical and Electronic Equipment (WEEE).

**NOTE:** Recyclers should sort plastic materials into resin streams for recycling based on the ISO 11469 plastic marking code on the plastic part. For any questions on plastic marking, please contact HP's Sustainability Contact.

### 1.0 Items Requiring Selective Treatment

**1.1 Items listed below are classified as requiring selective treatment.**

**1.2** Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm (MB, RAM, WLAN, Volume button BD, TP BD,)</td>
<td>5</td>
</tr>
<tr>
<td>Batteries, excluding Li-Ion batteries.</td>
<td>All types including standard alkaline, coin or button style batteries</td>
<td>0</td>
</tr>
</tbody>
</table>
| Li-Ion batteries. Include all Li-Ion batteries if more than one is provided with the product (such as a detachable notebook keyboard battery, RTC coin cell, etc.) | Battery(ies) are attached to the product by (check all that apply with an “x” inside the “[ ]“):
  - [ X ] screws
  - [ ] snaps
  - [ ] adhesive
  - [ ] other. Explain _____
  NOTE: Add detailed removal procedures including required tools in the sections 3.1 and 3.2. | 1                                     |
| Mercury-containing components                                                    | For example, mercury in lamps, display backlights, scanner lamps, switches, batteries | 0                                     |
| Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm              | Includes background illuminated displays with gas discharge lamps (11.6") | 1                                     |
| Cathode Ray Tubes (CRT)                                                          |                                                                       | 0                                     |
| Capacitors / condensers (Containing PCB/PCT)                                     |                                                                       | 0                                     |
| Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height |                                                                       | 0                                     |
| External electrical cables and cords                                            | DC Cable for External Power Supply                                      | 1                                     |
| Gas Discharge Lamps                                                              |                                                                       | 0                                     |
| Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs) |                                                                       | 0                                     |

EL-MF877-00
Template Revision C

Last revalidation date 09-May-2018

HPI instructions for this template are available at EL-MF877-01
### Item Description

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing radioactive substances</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>

### 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Electric screwdriver (Cross)</td>
<td>#1, #0</td>
</tr>
<tr>
<td>T8 electronic screw driver</td>
<td></td>
</tr>
<tr>
<td>Support fixture</td>
<td></td>
</tr>
<tr>
<td>Routing fixture</td>
<td></td>
</tr>
</tbody>
</table>

### 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment including the required steps to remove the external enclosure:

1. Follow steps described in Disassembly instruction (file attached)
2. If parts can be removed without using a tool, remove it first
3. Use correct screwdriver and torque value before unlock the screw.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
## MANUFACTURING PROCESS INSTRUCTIONS

### MECHANICAL ASSEMBLY

**MODEL : Balos**

### Sub-assembly name:

Balos 1.0-2.0拆机SOP

### Document No.:

Balos 1.0-2.0拆机SOP

### Written by:

朱亚

### Date:

2018/11/7

### Revision:

1.00

### Station Version List:

<table>
<thead>
<tr>
<th>Station</th>
<th>Version</th>
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<tbody>
<tr>
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<tr>
<td>ALL</td>
<td>0.2*</td>
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<tr>
<td>ALL</td>
<td>0.3*</td>
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<tr>
<td>ALL</td>
<td>0.4*</td>
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<tr>
<td>ALL</td>
<td>0.5*</td>
</tr>
<tr>
<td>ALL</td>
<td>0.6*</td>
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</table>

### Version Modify List:

<table>
<thead>
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<th>Date</th>
<th>Station</th>
<th>Content</th>
<th>Ver.</th>
<th>Design</th>
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</thead>
<tbody>
<tr>
<td>2018/8/25</td>
<td>ALL</td>
<td>首份試生产短線SOP制作</td>
<td>0.1*</td>
<td>郭潤梅</td>
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<tr>
<td>2018/8/30</td>
<td>ALL</td>
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<td>龍建軍</td>
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<tr>
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<td>ALL</td>
<td>站別調整</td>
<td>0.3*</td>
<td>龍建軍</td>
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<tr>
<td>2018/9/13</td>
<td>ALL</td>
<td>整份更新</td>
<td>0.4*</td>
<td>龍建軍</td>
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<tr>
<td>2018/9/18</td>
<td>ALL</td>
<td>站別調整</td>
<td>0.5*</td>
<td>胡鳳坤</td>
</tr>
<tr>
<td>2018/10/23</td>
<td>ALL</td>
<td>整份更新</td>
<td>0.6*</td>
<td>胡鳳坤</td>
</tr>
</tbody>
</table>

审核：胡鳳坤        制表：朱亚
Step:

1. Disassemble bottom case screws (6052B0387001)*2 (Fig 1)
   - Torque force: 2.0 ± 0.2 Kgf.cm
   - Pay attention to screw can’t loose, can’t slip into machine

Note: Carry PCB gently, can’t touch component on the board, any defect, Pls inform production leader immediately

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<thead>
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<tr>
<td>Cross electric screwdriver(#1)</td>
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</tr>
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</table>

Table: ZhuYa  Department: IE
1. Disassemble bottom case screws*2 (SET screw) (Fig 1)
   - Torque force: 2.0 ± 0.2 Kgf.cm
   - Pay attention to screw can’t loose, can’t slip into machine

Note: Carry PCB gently, can't touch component on the board, any defect, Pls inform production leader immediately
Step:

1. Disassemble bottom case screws M2.5x3.5 (6052B0466801)*4 (Fig 1)
   - Torque force: 2.0 ± 0.2 Kgf • cm
   - Pay attention to screw can’t loose, can’t slip into machine

Note: Carry PCB gently, can't touch component on the board, any defect, Pls inform production leader immediately

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<tr>
<td>T8 electronic screwdriver</td>
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</table>
Step:

1. Take apart top and bottom case
   - Pay attention to the remove order as below Fig show

Open Base, popup the hook

1. Take apart top and bottom case

Open Base, popup the hook

Note: Carry PCB gently, can't touch component on the board, any defect, Pls inform production leader immediately

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Table: ZhuYa  Department: IE
Step:

For 1.0

1. Disconnect 2nd CCD FFC, TP FFC, KB FFC from main board (Fig 1, 2)
2. Take apart top and bottom case

Note: Carry PCB gently, can't touch component on the board, any defect, Pls inform production leader immediately
Standard Operation Process

Document No. : Balos 1.0-2.0 disassembly SOP

Process Name : Disconnect FFC

Station : 5(2/2)

Ver. : 1.0

Date : 2018/11/7

**Step:**

For 2.0

1. Disconnect 2nd CCD FFC, TP FFC, KB FFC from main board (Fig 1, 2)
2. Take apart top and bottom case

---

**Note:** Carry PCB gently, can't touch component on the board, any defect, Pls inform production leader immediately

---

**Fixture List (Fixture Specification):**

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Table : ZhuYa  Department : IE
Standard Operation Process

Document No. : Balos 1.0-2.0 disassembly SOP
Process Name : Disassemble screw

Station : 6(1/1)
Ver. : 1.0
Date : 2018/11/7

Step :

1. Carry Top module
2. (For 2nd CCD only) disassemble Webcam/B screw M2*2 (6052B0156301)*1 (Fig1)
3. Disassemble bracket screws
   M2*2(6052B0156301)*2(Fig 1)
   ❖ Screwdriver type #1
   ❖ Torque force : 1.5 ± 0.2 Kgf.cm
   ❖ Pay attention to screw can’t loose
3. Put BRKT into material box

Note: Carry PCB gently, can't touch component on the board, any defect, Pls inform production leader immediately

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<tr>
<td>Cross electric screwdriver(#1)</td>
<td>1</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>
Step:

1. (For 2nd CCD only)

Disassemble Webcam screw

M1.6x2(6052B0204401)*1 (Fig 1)

- Screwdriver type #0
- Torque force: 1.0 ± 0.2 Kgf.cm
- Pay attention to screw can’t loose

2. Put daughter board into material box (as Fig 2 show)

---

Note: Carry PCB gently, can't touch component on the board, any defect, Pls inform production leader immediately

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<th>Fixture List(Fixture Specification)</th>
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</thead>
<tbody>
<tr>
<td>Cross electronic screwdriver(#0)</td>
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</tbody>
</table>

Table: ZhuYa  Department: IE
Standard Operation Process

Document No. : Balos 1.0-2.0 disassembly SOP
Process Name : Disconnect FFC

Station : 8(1/1)
Ver. : 1.0
Date : 2018/11/7

Step :

1. Disconnect Click pad FFC(1.0 6035B0187701 HanQuan/ 6035B0189901JiuDong)
   (2.0 6035B0188801 HanQuan /
   6035B0189601 JiuDong) (Fig1,2))

Note: Carry PCB gently, can't touch component on the board, any defect, Pls inform production leader immediately

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</table>

Table : ZhuYa  Department : IE
Step:

1. Remove Keyboard Mylar (6054B2106301) (Fig 1)

Note: Carry PCB gently, can't touch component on the board, any defect, Pls inform production leader immediately

<table>
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</table>

Table: ZhuYa  Department: IE
**Step:**

1. Disassemble click pad dimple bracket (6053B1600601) screws M2*2.5 (6052B0120001) *3

   - Screwdriver type #1
   - Torque force: 1.5 ± 0.2 Kg cm
   - Pay attention to screw can’t loose

2. Put bracket in the box

---

**Note:** Carry PCB gently, can't touch component on the board, any defect, Pls inform production leader immediately

<table>
<thead>
<tr>
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</thead>
<tbody>
<tr>
<td>Cross electric screwdriver(#1)</td>
<td></td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

**Table:** ZhuYa  **Department:** IE
1. Disassemble Click pad screws
   - M2*2(6052B0388301) * 3 (Fig 1)
   - Screwdriver type:#1
   - Torque force : 1.5 ± 0.2 Kgf. cm
   - Pay attention to screw can’t loose
2. Put click pad module in the box

Fig 1

Note: Carry PCB gently, can't touch component on the board, any defect, Pls inform production leader immediately

<table>
<thead>
<tr>
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<tbody>
<tr>
<td>Cross electric screwdriver(#1)</td>
<td>1</td>
<td></td>
<td></td>
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</tbody>
</table>
Step:

1. Disassemble hot-melt to separate KB/bracket, KB and waterproof Mylar.

Note: Carry PCB gently, can't touch component on the board, any defect, Pls inform production leader immediately

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<th>Qty</th>
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<th>Qty</th>
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</thead>
<tbody>
<tr>
<td>Disassemble hot-melt machine</td>
<td>1</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

Table: ZhuYa  Department: IE
Step:

1. Disassemble battery screws M2.5*4(6052A0034501)*4
   ❖ Torque force: 2.0 ± 0.2 Kgf.cm
   ❖ Pay attention to screw can’t loose, can’t slip into machine
2. Put the battery in the box

Note: Carry PCB gently, can't touch component on the board, any defect, Pls inform production leader immediately

<table>
<thead>
<tr>
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<tr>
<td>Cross electric screwdriver(#1)</td>
<td>1</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

Table: ZhuYa Department: IE
Standard Operation Process

Document No. : Balos 1.0-2.0 disassembly SOP  Station : 14(1/2)
Process Name : Disassemble Speaker&RTC  Ver. : 1.0  Date : 2018/11/7

Step :
1. Disassemble screw M2*1.8(6052B0386901)*4(Fig 1)
   - Torque force : 1.5 ± 0.2Kgf.cm
   - Pay attention to screw can’t loose, can’t slip into machine

Note: Carry PCB gently, can't touch component on the board, any defect, Pls inform production leader immediately

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<td>Cross electric screwdriver(#1)</td>
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</table>

Table : ZhuYa  Department : IE
**Step:**

1. Tear off the adhesive tape, carry the speaker Cable CNTR from MB
2. Separate RTC Battery from Base
3. Put the speaker in the box

**Note:** Carry PCB gently, can't touch component on the board, any defect, Pls inform production leader immediately

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<tr>
<td></td>
<td></td>
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</table>

Table: ZhuYa  Department: IE
Step:

1. Disconnect DC in cable from M/B CNTR
2. Tear off the aluminum foil
3. Disconnect Touch Cable from M/B CNTR

Note: Carry PCB gently, can't touch component on the board, any defect, Pls inform production leader immediately

<table>
<thead>
<tr>
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<tbody>
<tr>
<td></td>
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</table>

Table: ZhuYa  Department: IE
**Standard Operation Process**

**Process Name:** Disconnect EDP-Cable & Antenna  
**Ver.:** 1.0  
**Date:** 2018/11/7

---

**Step:**

1. Disconnect EDP Cable from M/B CNTR
2. Disconnect Antenna cable

---

**Note:** Carry PCB gently, can't touch component on the board, any defect, Pls inform production leader immediately

---

**Fixture List (Fixture Specification)**

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</thead>
</table>

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Table: ZhuYa  
Department: IE
Standard Operation Process

Document No. : Balos 1.0-2.0 disassembly SOP
Process Name : Remove FFC & Rubber

Station : 17(1/2)  Ver. : 1.0  Date : 2018/11/7

**Step:** For 1.0

1. Disconnect Audio/B FFC from M/B CNTR
2. Remove Rubber (6054B2107101) from Audio/B

---

Note: Carry PCB gently, can't touch component on the board, any defect, PIs inform production leader immediately

<table>
<thead>
<tr>
<th>Fixture List (Fixture Specification)</th>
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Table: ZhuYa  Department: IE
Standard Operation Process

Document No. : Balos 1.0-2.0 disassembly SOP  
Process Name : Remove FFC & Rubber  
Station : 17(2/2)  
Ver. : 1.0  
Date : 2018/11/7

**Step:**

For 2.0

1. Disconnect Audio / USB FFC from M/B CNTR
2. Remove Rubber (6054B2107101) from Audio/B

---

**Note:** Carry PCB gently, can't touch component on the board, any defect, PIs inform production leader immediately

---

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Table : ZhuYa  
Department : IE
Step:

1. Disassemble WLAN card screw M2*3(6052B0156101)*1 (Fig 1)
   - Torque force: 1.5 ± 0.2 Kgf.cm
   - Pay attention to screw can’t loose, can’t slip into machine

FOR SSD SKU
2. Disassemble SSD CARD screw M2*3(6052B0156101)*1 (Fig 2)
   - Torque force: 1.5 ± 0.2 Kgf.cm
   - Pay attention to screw can’t loose, can’t slip into machine
3. Put material into box

Note: Carry PCB gently, can't touch component on the board, any defect, Pls inform production leader immediately

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<tbody>
<tr>
<td>Cross electronic screwdriver(#1)</td>
<td>1</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>
Step:

For 1.0

1. Disassemble the M/B screws
   M2.5*4(6052A0034501)*4 (Fig. 1)
   - Torque force: 2.0 ± 0.2 Kgf. Cm
   - Pay attention to screw can’t loose, can’t slip into machine
   - The position of the lock screw on the main board has the Δ symbol

Note: Carry PCB gently, can’t touch component on the board, any defect, PIs inform production leader immediately

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Step 1. Disassemble the M/B screws M2.5*4(6052A0034501)*4 (Fig. 1)
- Torque force: 2.0 ± 0.2 Kgf. Cm
- Pay attention to screw can’t loose, can’t slip into machine
- The position of the lock screw on the main board has the Δ symbol

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Step:

For 1.0

1. Disassemble the M/B screws
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- Torque force: 2.0 ± 0.2 Kgf. Cm
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Table: ZhuYa  Department: IE
Step:

For 2.0

1. Disassemble the M/B screws M2.5*4(6052A0034501)*3 (Fig. 1)
   - Torque force: 2.0 ± 0.2 Kgf. Cm
   - Pay attention to screw can’t loose, can’t slip into machine
   - The position of the lock screw on the main board has the Δ symbol

Cross electric screwdriver (#1)                    1

Note: Carry PCB gently, can’t touch component on the board, any defect, Pls inform production leader immediately

Table: ZhuYa    Department: IE
Standard Operation Process

Document No. : Balos 1.0-2.0 disassembly SOP  
Process Name : Disassemble Screw  
Station : 21(1/2)  
Ver. : 1.0  
Date : 2018/11/7

**Step:**

1. Disassemble the M/B screw  
   M2.5*4(6052A0034501)*1 (Fig 1)
2. Disassemble the screws  
   M2.5*4(6052A0034501)*2 Audio/B (Fig 1)
   - Torque force: 2.0 ± 0.2 Kgf. Cm  
   - Pay attention to screw can’t loose, can’t slip into machine  
   - The position of the lock screw on the main board has the Δ symbol

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**Table:**

<table>
<thead>
<tr>
<th>Fixture List (Fixture Specification)</th>
<th>Qty</th>
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<th>Qty</th>
</tr>
</thead>
<tbody>
<tr>
<td>Cross electric screwdriver (#1)</td>
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<td></td>
</tr>
</tbody>
</table>

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Note: Carry PCB gently, can’t touch component on the board, any defect, Pls inform production leader immediately.

---

Fig 1
Step:

For 2.0

1. Disassemble the MB screw
   M2.5*4(6052A0034501)*1 (Fig 1)

2. Disassemble the Audio/B screw
   M2.5*4(6052A0034501)*2 (Fig 1)
   - Torque force: 2.0 ± 0.2 Kgf. Cm
   - Pay attention to screw can’t loose, can’t slip into machine
   - The position of the lock screw on the main board has the Δ symbol

Note: Carry PCB gently, can't touch component on the board, any defect, Pls inform production leader immediately

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</tbody>
</table>
Step: For 1.0

1. Remove Type C BRKT (6053B1599301) from M/B (Fig 1)
2. Remove M/B in the lower case
   - Tilt the left front 45 degrees to remove the MB
   - Drop out thermal module hook

Note: Carry PCB gently, can't touch component on the board, any defect, PIs inform production leader immediately

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<thead>
<tr>
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<tbody>
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<td>Micro ion fan</td>
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</table>

Table: ZhuYa  Department: IE
**Step:**

For 2.0

1. Remove Type C BRKT (6053B1599301) from M/B (Fig 1)
2. Remove M/B in the lower case
   - Tilt the left front 45 degrees to remove the MB
   - Drop out thermal module hook

---

**Note:** Carry PCB gently, can't touch component on the board, any defect, PIs inform production leader immediately

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</tbody>
</table>

Table: ZhuYa  Department: IE
Standard Operation Process

Document No. : Balos 1.0-2.0 disassembly SOP
Process Name : Remove DC in&Board

Station : 23(1/2)
Ver. : 0.60
Date : 2018/10/23

Step :

For 1.0

1. Remove DC Bracket (6053B1601401), Cable (Fig 1)
2. Remove Audio/B group in Base (Fig 2)

Note: Carry PCB gently, can't touch component on the board, any defect, Pls inform production leader immediately

<table>
<thead>
<tr>
<th>Fixture List (Fixture Specification)</th>
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<tbody>
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</tbody>
</table>

Table : ZhuYa   Department : IE
Standard Operation Process

Document No. : Balos 1.0-2.0 disassembly SOP
Process Name : remove DC in · Board

Step :

For 2.0

1. Remove DC Bracket (6053B1601401), Cable (Fig 1)
2. Remove Audio/B ,USB/B group in Base (Fig 2)

Note: Carry PCB gently, can't touch component on the board, any defect, Pls inform production leader immediately

<table>
<thead>
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<td></td>
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</tbody>
</table>

Table : ZhuYa  Department : IE
**Step:**

For 1.0

1. Placed on the fixture, face B up (Fig 1)
2. Remove the screw M2*3 (6052B0156101) *4.
   - Torque force: 1.5 ± 0.2Kgf. cm
   - Note that the screws are not slippery.
   - Locking order: 1 → 2 → 3 → 4
   - Do not touch the solder paste during work.
3. Material placed in the box

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**Fixture List (Fixture Specification)**

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<tr>
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</tr>
<tr>
<td>Thermal module support fixture</td>
<td>1</td>
</tr>
<tr>
<td>Ion fan</td>
<td>1</td>
</tr>
</tbody>
</table>

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**Table:** ZhuYa  **Department:** IE
### Step:

For 2.0

1. Place thermal module on the fixture, face B side up (Fig 1)
2. Remove the screws M2*3 (6052B0156101) *4.
   - Torque force : 1.5 ± 0.2Kgf. cm
   - Note that the screws are not slippery.
   - Locking order: 1 → 2 → 3 → 4

3. Do not touch the solder paste
4. Put module in the box

---

**Note:** Carry PCB gently, can't touch component on the board, any defect, Pls inform production leader immediately

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</table>

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**Table:** ZhuYa, **Department:** IE
**Step:**

1. Open the top and bottom module, then disassemble screw M2.5*5(6052A0003501)*7 Hinge (Figure 1: mark 1,2,3,4).
   - Torque force : 3.0 ± 0.2 Kgf.cm
   - Screw cannot make scratch on the unit or slip into the unit.
2. Separate the top and bottom module and put base in the box.

**Note:** Carry PCB gently, can't touch component on the board, any defect, Pls inform production leader immediately

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<tbody>
<tr>
<td>Cross electric screwdriver (#1)</td>
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<td></td>
<td></td>
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</tbody>
</table>

Table: ZhuYa  Department: IE
Step:

FOR Non-touch:
1. Disassemble B-Cover & A-Cover
Caution: Please disassemble bezel softly to avoid the crack of panel.

Tips:
1. Take apart the bezel and panel from the white zone marked in the Fig.
2. Disassemble the top, left and right side in clockwise direction or counter-clockwise direction and finally disassemble the bottom side.

Note: Carry PCB gently, can't touch component on the board, any defect, PIs inform production leader immediately

<table>
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Table: ZhuYa  Department: IE
Standard Operation Process

Document No.: Balos 1.0-2.0 disassembly SOP
Process Name: Disassemble B-Cover & A-Cover

Step:
1. Disconnect cable from bezel.
2. Refer to the following Fig for disconnect sequence: 1→2→3→4→5.

Caution:
1. On the upper left or right corner, take apart A cover & B cover.
2. In location 4, avoid A cover scratched by bezel hook.

Note: Carry PCB gently, can't touch component on the board, any defect, Pls inform production leader immediately.

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<tr>
<td>Micro ion fan</td>
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<td>Routing fixture</td>
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Table: ZhuYa  Department: IE
Standard Operation Process

Document No. : Balos 1.0-2.0 disassembly SOP  
Station : 27(1/1)  
Process Name : Disassemble Hinge Cap Rubber  
Ver. : 1.0  
Date : 2018/11/7

Step :
1. Drag cable to loose the hinge cap rubber and then take out the rubber (Fig 1)

Note: Carry PCB gently, can't touch component on the board, any defect, Pls inform production leader immediately

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<td>Routing fixture</td>
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<td></td>
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</table>

Table : ZhuYa  
Department : IE
Step:

1. Remove panel screw M2*2.5 (6052B0156101) * 4 (Fig1: mark 1, 2, 3, 4)
   - Cross electric screwdriver #1
   - Torque force: 1.5 ± 0.2Kgf.cm
   - Screw cannot make scratch on the unit.
   - Removal sequence: 1, 2, 3, 4.

Note: Carry PCB gently, can't touch component on the board, any defect, Pls inform production leader immediately.

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<td>Cross electric screwdriver</td>
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Table: ZhuYa  Department: IE
Step:

1. Turnover the panel and put on the foam and then disassemble COMN (Fig 1)
   - Caution: do not disassemble the panel by a single hand.
2. Put the panel in the box.

Note: Carry PCB gently, can't touch component on the board, any defect, Pls inform production leader immediately

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Table: ZhuYa  Department: IE
Note: Carry PCB gently, can't touch component on the board, any defect, Pls inform production leader immediately

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<tr>
<td>Cross electric screwdriver #1</td>
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</table>
Step:

1. Remove hinge screw
M2.5*2.5(6052B0466901) *6 (Fig1: mark 1, 2, 3).
   ➢ Cross electric screwdriver #1
   ➢ Torque force : 3± 0.2 Kg.cm
   ➢ Screw can not make scratch on the unit.
2. Disassemble the left and right hinge and put it into the box.

Note: Carry PCB gently, can't touch component on the board, any defect, Pls inform production leader immediately

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Table: ZhuYa  Department: IE
Standard Operation Process

Document No. : Balos 1.0-2.0 disassembly SOP
Process Name : Disassemble Upper Bracket/Camera

Station : 32(1/1)
Ver. : 0.30
Date : 2018/10/23

Step :

For Non-Touch
1. Remove screw M2*2.5 (6052B0120001)*2 (Fig 1: mark 1,2)
   - Cross electric screwdriver #1
   - Torque force : 1.5 ± 0.2 Kgf.cm
   - Screw can not make scratch on the unit.

For Non-Touch/Touch
2. Remove aluminized paper and camera gum (Fig 2).
3. Put the material in the box.

Note: Carry PCB gently, can't touch component on the board, any defect, Pls inform production leader immediately

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</table>

Table : ZhuYa  Department : IE
Step:
1. Remove antenna copper foil and disassemble antenna from card slot of A-Cover hook (Fig 1).

Note: Carry PCB gently, can't touch component on the board, any defect, Pls inform production leader immediately.

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<tr>
<td>Routing fixture</td>
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Table: ZhuYa  Department: IE
Step:
1. Remove gum and disassemble G-Sensor/B(1310A3009701).
2. Open CONN latch and get G-sensor.
3. Put material in the box.

Note: Carry PCB gently, can't touch component on the board, any defect, PIs inform production leader immediately.
Step:

1. Open camera, LED/B, CONN Latch and take out camera, LED/B.
2. Take out CCD Cable from A-Cover hook and slot

Note: Carry PCB gently, can't touch component on the board, any defect, Pls inform production leader immediately

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